

SiC Six-pack Module PAAC12400CM

Features

- Silicon Carbide MOSFET
- Low R_{DSon}
- Low Switching Losses
- Si₃N₄ Ceramic
- PinFin Base Plate

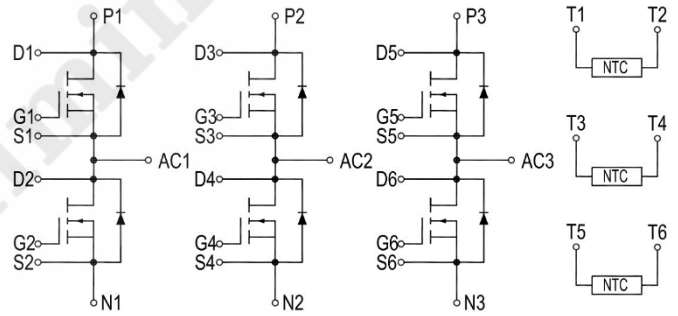


Applications

- Automotive Applications
- EV/HEV
- Motor Drives

Standards Benefits

- Improve System Efficiency
- Increase Power Density
- Reduce Heat Sink Requirement
- Reduce System Cost



Order Information

Part Number	Package	Marking
PAAC12400CM	HPD	PAAC12400CM



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1. Maximum Ratings

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value	Unit	Test Conditions
Drain - Source Voltage	V_{DS}	1200	V	
Gate - Source Voltage (Dynamic)	V_{GSmax}	-8 / +19	V	AC (f > 1Hz)
Gate - Source Voltage(static) turn-on gate voltage turn-off gate voltage	$V_{GS,on}$ $V_{GS,off}$	+15 -3	V	Static
Continuous Drain Current	I_D	400	A	$V_{GS} = 15\text{V}$ $T_F = 60^\circ\text{C}$
Power Dissipation	P_D	1000	W	
Operating Junction Temperature	T_J	-40 To +150	$^\circ\text{C}$	

2. Electrical Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise (Per Position)

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200	/	/	V	
Gate Threshold Voltage	$V_{GS(th)}$	1.8	2.9	/	V	$V_{DS} = V_{GS}$ $I_D = 141.6\text{mA}$ $T_J = 25^\circ\text{C}$
Reverse Bias Drain Current	I_{DSS}	/	15	800	μA	$V_{GS} = 0\text{V}$ $V_{DS} = 1200\text{V}$

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Reverse Bias Drain Current	I_{DSS}	/	1	/	μA	$V_{GS} = -3V$ $V_{DS} = 1200V$
Gate-Source Leakage Current	I_{GSS}	/	20	2000	nA	$V_{GS} = 15V$ $V_{DS} = 0V$
Drain-Source On-State Resistance	$R_{DS(on)}$	/	3.13	4.07	m Ω	$V_{GS} = 15V$ $I_D = 400A$
Turn-on Energy	E_{on}	/	39.62	/	mJ	$V_{DS} = 800V$ $I_{DS} = 400A$ $V_{GS} = -3V/15V$ $R_G = 5.0\Omega$ $L = 20\mu H$
Turn-off Energy	E_{off}	/	28.90	/		
Turn-On Delay Time	$T_{d(on)}$	/	126.6	/	nS	
Rise Time	T_r	/	263.2	/		
Turn-Off Delay Time	$T_{d(off)}$	/	265.9	/		
Fall Time	T_f	/	83.8	/		
Internal Gate Resistance	$R_{G(int)}$	/	0.43	/	Ω	$f = 100kHz$ $V_{AC} = 25mV$
Input Capacitance	C_{iss}	/	51.8	/	nF	$V_{GS} = 0V$ $V_{DS} = 800V$ $f = 100kHz$ $V_{AC} = 25mV$
Output Capacitance	C_{oss}	/	1.90	/	nF	
Reverse Transfer Capacitance	C_{rss}	/	93.0	/	pF	
Thermal Resistance from Junction to Cooling Fluid	$R_{\theta JF}$	/	0.09	/	$^{\circ}C/W$	per MOSFET, $\Delta V/\Delta t = 10.0dm^3/min;$ $T_F = 60^{\circ}C$

3. Reverse Diode Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise (Per Position)

Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Diode Forward Voltage	V_{SD}	5.2	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 200\text{A}$ $T_J = 25^\circ\text{C}$
		4.7	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 200\text{A}$ $T_J = 150^\circ\text{C}$
Continuous Diode Forward Current	I_S	200	/	A	$V_{GS} = -3\text{V}$
Reverse Recover Time	t_{rr}	25.4	/	ns	$V_{GS} = -3\text{V}$ $I_{SD} = 400\text{A}$ $V_R = 800\text{V}$
Reverse Recovery Charge	Q_{rr}	813.2	/	μC	
Peak Reverse Recovery Current	I_{rrm}	52.2	/	A	
Reverse Recovery Energy	E_{RR}	0.23	/	mJ	$V_{GS} = -3\text{V}$ $I_{SD} = 400\text{A}$ $V_R = 800\text{V}$ $dI_f/dt = 3900\text{A}/\mu\text{s}$

4. Module Physical Characteristics

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Storage Temperature	T_{stg}	-40	/	125	$^\circ\text{C}$	

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Weight	W	/	720	/	g	
Mounting Torque	M	1.8	/	2.2	N·m	Screw M4
Comparative Tracking Index	CTI	200	/	/		

5. NTC Thermistor Characteristics

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Rated Resistance	R_{NTC}	/	5	/	$k\Omega$	$T_{NTC} = 25^{\circ}C$
Resistance Tolerance	$\Delta R/R$	-5	/	5	%	$T_{NTC} = 25^{\circ}C$
B-value	$B_{25/50}$	/	3380	/	K	$T_2 = 50^{\circ}C$
B-value	$B_{25/85}$	/	3435	/	K	$T_2 = 80^{\circ}C$
B-value	$B_{25/100}$	/	3485	/	K	$T_2 = 100^{\circ}C$
Power Dissipation	P_{NTC}	/	/	10	mW	$T_{NTC} = 25^{\circ}C$

6. Typical Performance

At $T_J = 25^\circ\text{C}$, unless specified otherwise (Per Position)

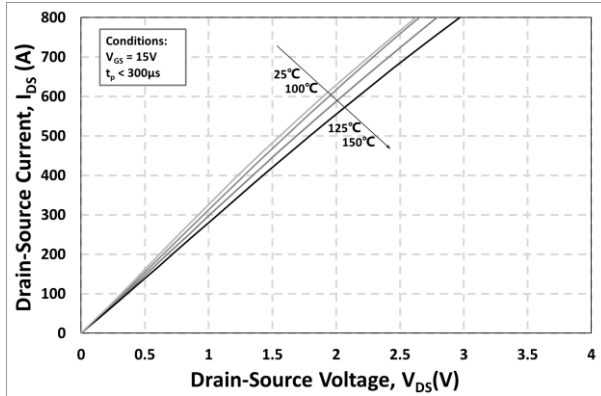


Figure 1. Output Characteristics for Various Junction Temperatures

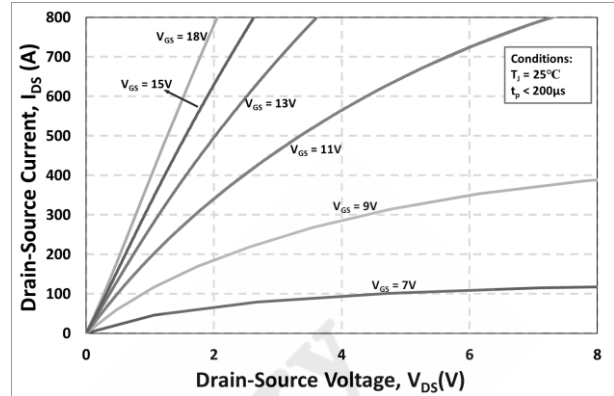


Figure 2. Output Characteristics $T_J = 25^\circ\text{C}$

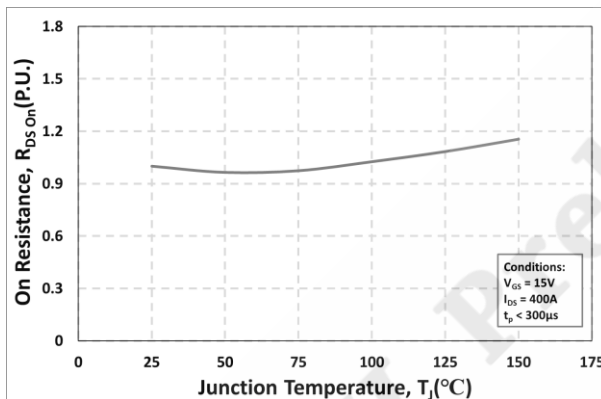


Figure 3. Normalized On-State Resistance vs. Junction Temperature

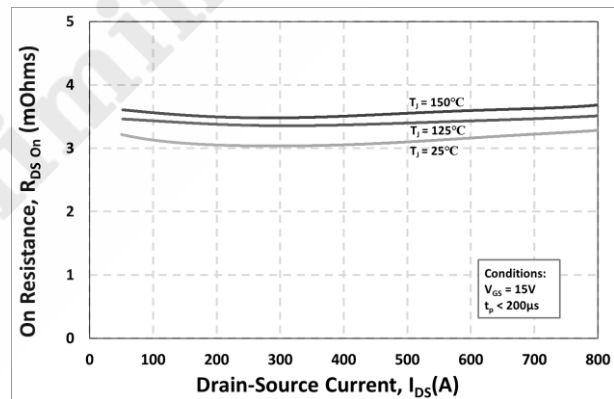


Figure 4. On-Resistance vs. Drain Current Various Temperatures

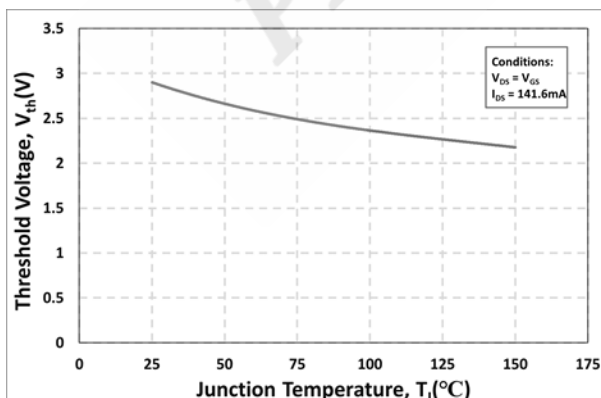


Figure 5. Threshold Voltage vs. Junction Temperature

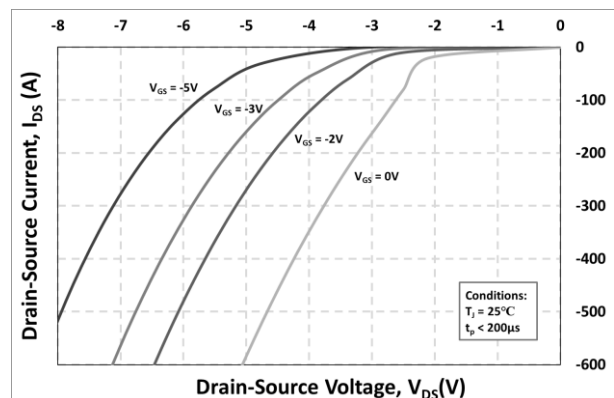


Figure 6. Body Diode Characteristics

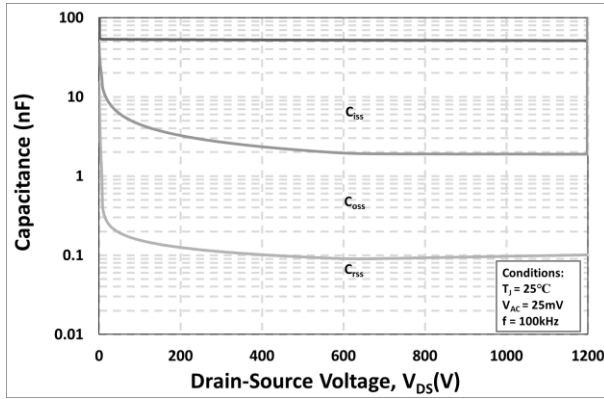


Figure 7. Capacitances vs. Drain-Source Voltage

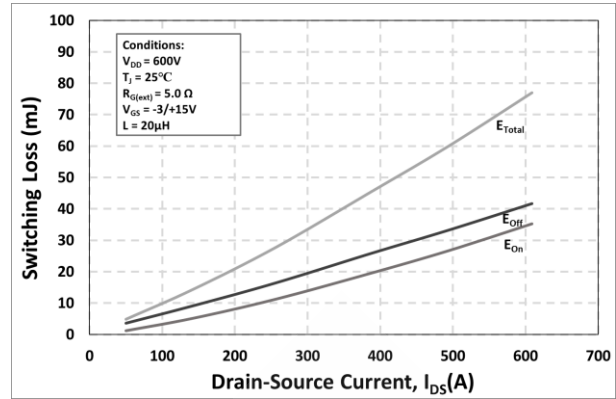


Figure 8. Switching Loss vs. Drain-Source Current ($V_{DS} = 600\text{ V}$)

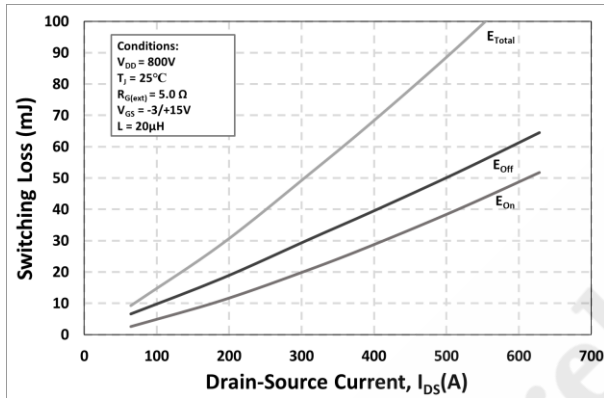


Figure 9. Switching Loss vs. Drain-Source Current ($V_{DS} = 800\text{ V}$)

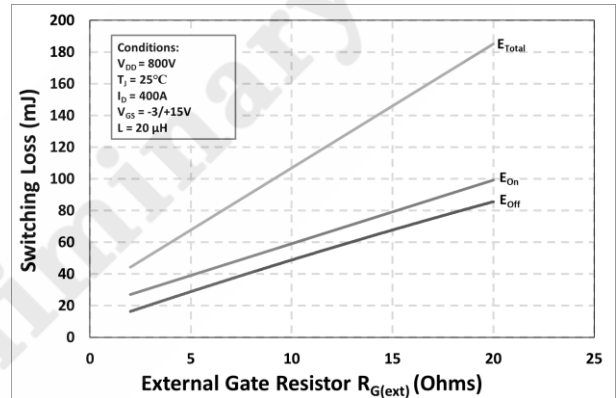


Figure 10. Switching Loss vs. External Gate Resistance

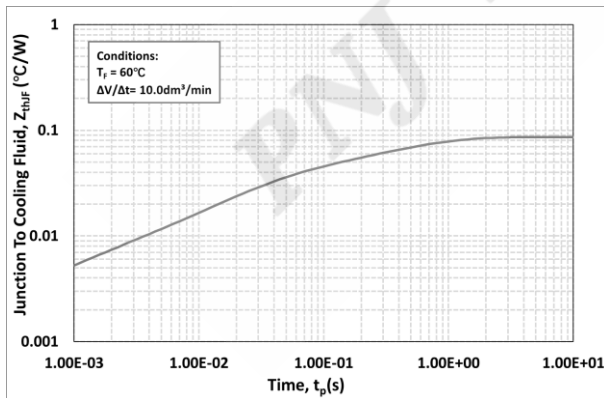


Figure 11. Transient Thermal Impedance (Junction – Cooling Fluid)

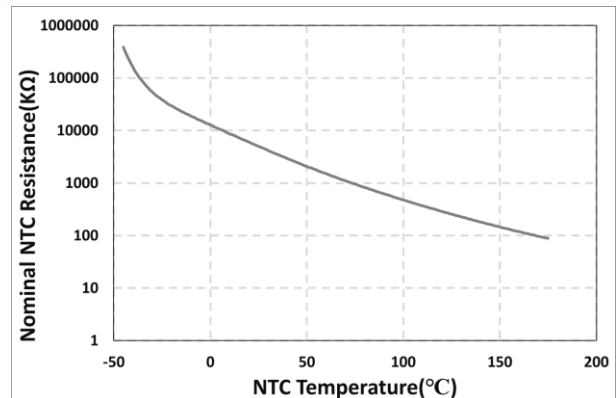


Figure 12. Nominal NTC Resistance vs. NTC Temperature

7. Definitions

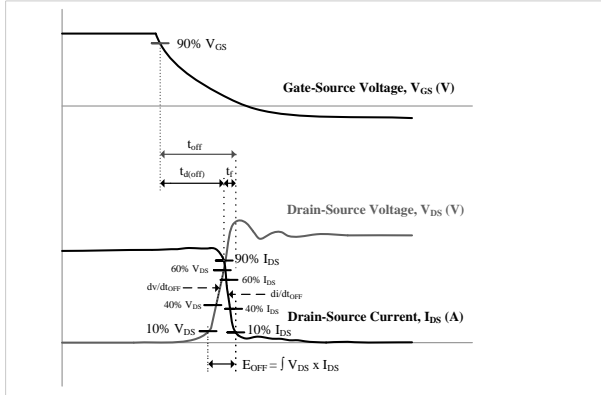


Figure 13. Turn-off Transient Definitions

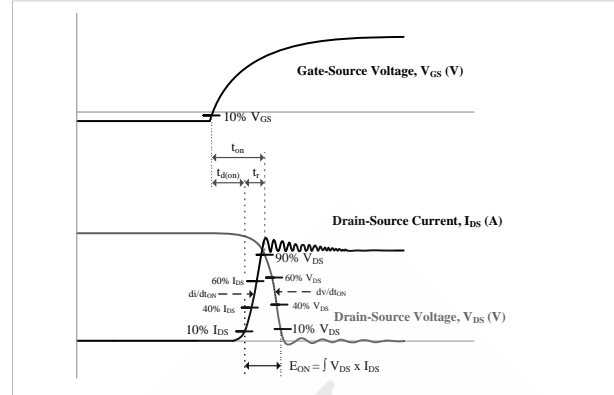


Figure 14. Turn-on Transient Definitions

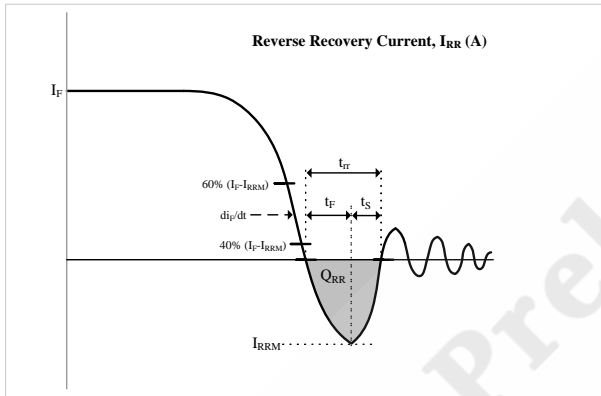


Figure 15. Reverse Recovery Definitions

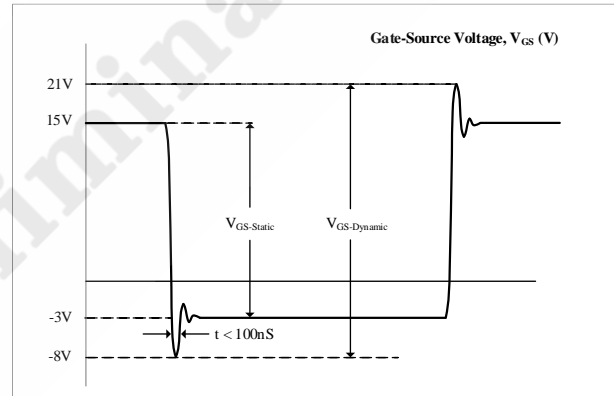
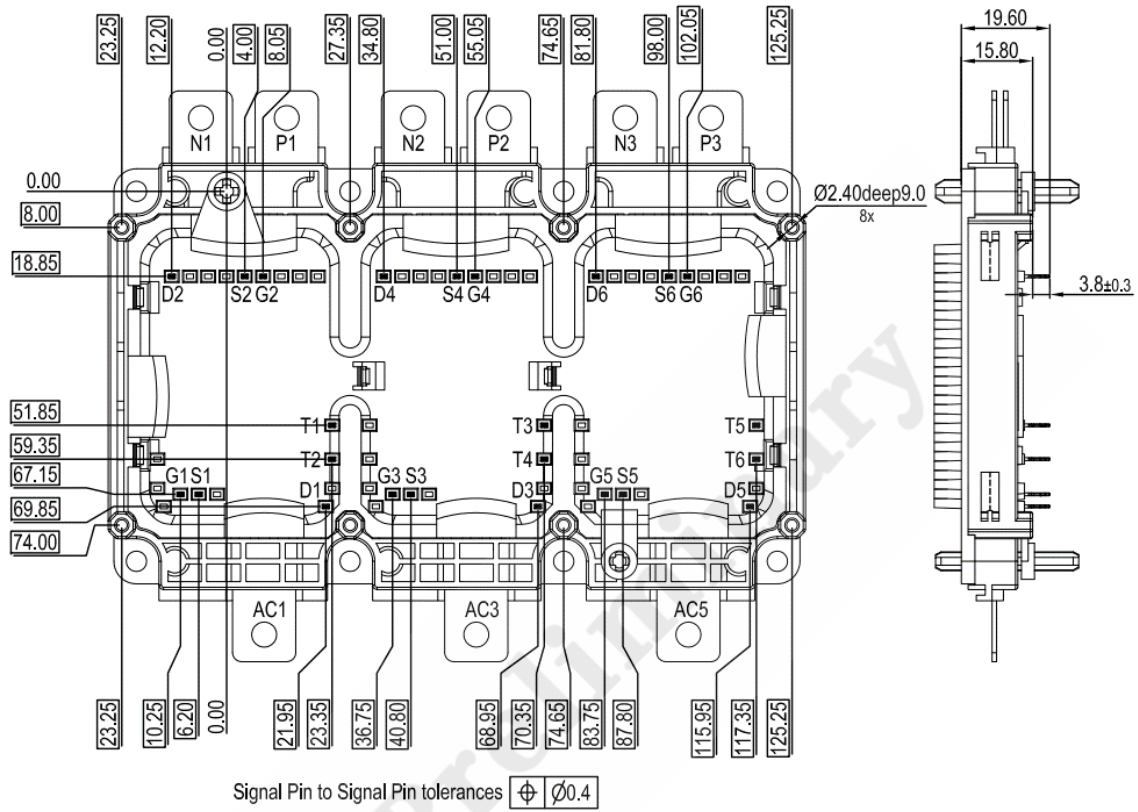


Figure 16. V_{GS} Transient Definitions

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8. Package Outlines



Drawing and Dimensions



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